





## **1 Product profile**

### 1.1 General description

Two planar PIN diodes in common cathode configuration in a SOT323 small SMD plastic package.

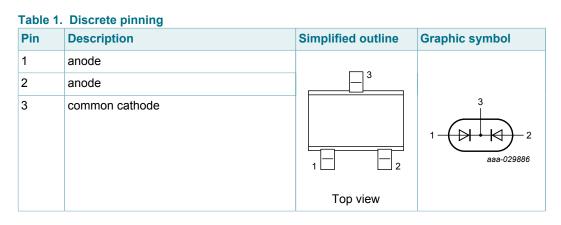
### 1.2 Features and benefits

- Two elements in common cathode configuration in a small-sized plastic SMD package
- · Low diode capacitance
- Low diode forward resistance

### **1.3 Applications**

· General RF applications

### 2 Pinning information



## **3 Ordering information**

Table 2. Ordering information					
Type number	Package				
	Name	Description	Version		
BAP50-05W	-	plastic surface-mounted package; 3 leads	SOT323		



# 4 Marking

Table 3. Marking code				
Type number	Marking code			
BAP50-05W	W4%			

### 5 Limiting values

#### Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>R</sub>	continuous reverse voltage		-	50	V
l <sub>F</sub>	continuous forward current		-	50	mA
P <sub>tot</sub>	total power dissipation	T <sub>sp</sub> ≤ 90 °C	-	240	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

## **6** Thermal characteristics

Table 5. Thermal characteristics						
Symbol	Parameter	Conditions	Тур	Unit		
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		250	K/W		

## 7 Characteristics

#### Table 6. Characteristics

 $T_i = 25$  °C unless otherwise specified.

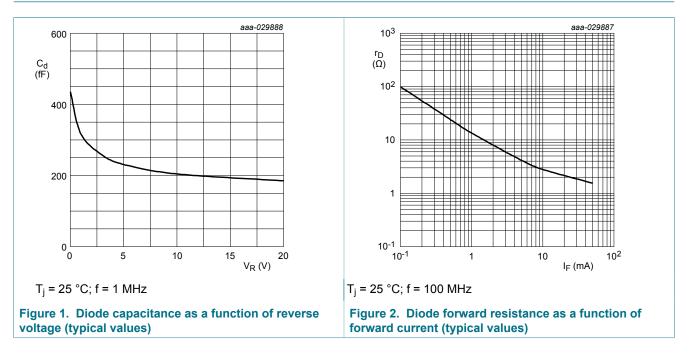
Symbol	Parameter	Conditions	Min	Тур	Max	Unit		
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 50 mA	-	0.95	1.1	V		
V <sub>R</sub>	reverse voltage	I <sub>R</sub> = 10 μA	50	-	-	V		
I <sub>R</sub>	reverse current	V <sub>R</sub> = 50 V	-	-	100	nA		
C <sub>d</sub>	diode capacitance	f = 1 MHz (see <u>Figure 1</u> )						
		V <sub>R</sub> = 0 V	-	0.45	-	pF		
		V <sub>R</sub> = 1 V	-	0.35	0.6	pF		
		V <sub>R</sub> = 5 V	-	0.3	0.5	pF		
r <sub>D</sub>	diode forward resistance	f = 100 MHz (see <u>Figure 2</u> )						
		I <sub>F</sub> = 0.5 mA	[1] -	25	40	Ω		
		I <sub>F</sub> = 1 mA	[1] -	14	25	Ω		
		I <sub>F</sub> = 10 mA	[1] -	3	5	Ω		
ISL i	isolation	$V_R = 0 V (see Figure 4)$						
		f = 900 MHz	-	19	-	dB		
		f = 1800 MHz	-	15.7	-	dB		
		f = 2450 MHz	-	13.5	-	dB		
L <sub>ins</sub>	insertion loss	See Figure 3.						
		I <sub>F</sub> = 0.5 mA						
		f = 900 MHz	-	1.84	-	dB		
		f = 1800 MHz	-	1.90	-	dB		
		f = 2450 MHz	-	1.92	-	dB		
		I <sub>F</sub> = 1 mA						
		f = 900 MHz	-	1.08	-	dB		
		f = 1800 MHz	-	1.13	-	dB		
		f = 2450 MHz	-	1.17	-	dB		
		I <sub>F</sub> = 10 mA						
		f = 900 MHz	-	0.26	-	dB		
		f = 1800 MHz	-	0.30	-	dB		
		f = 2450 MHz	-	0.36	-	dB		
τι	charge carrier life time	when switched from I <sub>F</sub> = 10 mA to I <sub>R</sub> = 6 mA; R <sub>L</sub> = 100 $\Omega$ ; measured at I <sub>R</sub> = 3 mA	-	1.05	-	μs		

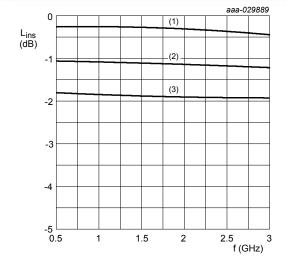
[1] Guaranteed on AQL basis; inspection level S4, AQL 1.0

BAP50-05W

Silicon PIN diode

### 8 Graphical data



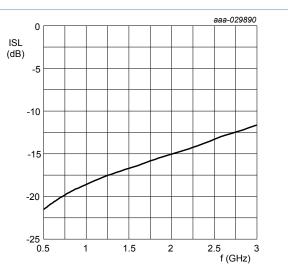


Diode inserted in series with a 50  $\Omega$  strip line circuit and biased via the analyzer T-network; T<sub>amb</sub> = 25 °C

(1) I<sub>F</sub> = 10 mA (2) I<sub>F</sub> = 1 mA

(3) I<sub>F</sub> = 0.5 mA

Figure 3. Insertion loss of the diode as a function of frequency (typical values)



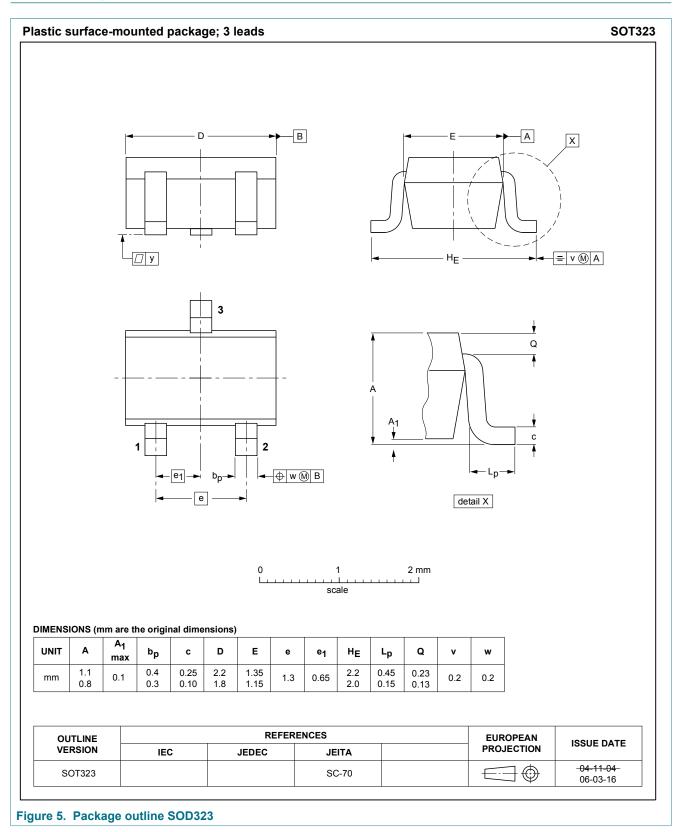
Diode zero-biased and inserted in series with a 50  $\Omega$  strip line circuit and biased via the analyzer T-network; T<sub>amb</sub> = 25 °C

Figure 4. Isolation of the diode as a function of frequency (typical values)

**BAP50-05W** 

Silicon PIN diode

## 9 Package outline



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### Silicon PIN diode

## 10 Revision history

Table 7. Revision history					
Document ID	Release date	Data sheet status	Change notice	Supersedes	
BAP50-05W v.3.1	20190208	Product data sheet	-	BAP50-05W v.3	
Modifications:	aligned the title of the data sheet with the description on the Internet				
BAP50-05W v.3	20181126	Product data sheet	-	BAP50-05W v.2.1	
Modifications:	<ul> <li><u>Section 1.2</u> "Features and benefits" has been updated.</li> <li>The "Legal information" pages have been updated.</li> </ul>				
BAP50-05W v.2.1	20010417	Product data sheet	-	BAP50-05W v.1	

## **11 Legal information**

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] [3] The term 'short data sheet' is explained in section "Definitions".

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**Product data sheet** 

### **NXP Semiconductors**

# **BAP50-05W**

#### Silicon PIN diode

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Product data sheet

BAP50-05W

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Silicon PIN diode

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